

Appl. No. 10/664,877  
Amendment dated: June 28, 2005  
Reply to OA of: April 4, 2005

**Amendments to the Specification:**

On page 7, please replace paragraph [0026] with the following amended paragraph.

[0026] As mentioned above, we know that in each thermal enhance package, the pellets 66 connect the heat spreader unit 71 and the substrate unit 51 so that the heat arisen out of the chip 61 is transmitted to the heat spreader 71 not only through the encapsulation unit [[641]] 64 but also through the pellets 66. In addition, the heat spreader unit 71 is electrically connected to the substrate unit 51 via the pellets 66 as a shielding as shown in FIG. 14. Thus the electrical performance of the thermal enhance package is enhanced and the shielding can prevent the effect of the magnetoelectricity from affecting the thermal enhance package.